

# **Product Change Notification**

## CN-202212019F

Issue date: 06 Jan 2023
Effective date: 20 Apr 2023

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



# Change of back side metallization thickness - wave 4

# Change Category

[X] Wafer Assembl Fab [] Process [ ] Test [ ] Product Marking Design Process [X] Location [ ] Mechanical [] Errata [] Wafer [ ] Test Assembl Specification Fab **Process** Electrical [] Test Material Materials Packing/Shipping/Labelin spec./Tes Equipmen Γ1 t [] t Assembl coverage Wafer Fab Location Location

# **Details of this change**

The back side metallization thickness will be changed from 2.25  $\mu m$  to 1.75  $\mu m$ .

The change of back side metallization thickness is combined with the introduction of 8 inch wafer diameter for product type PBSS5350D.

Current products: back side metallization thickness 2.25 µm; 8 inch (where affected) and 6 inch (where affected)

Changed products: back side metallization thickness 1.75 µm; 8 inch

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

SQR\_202212019F.pdf: <a href="https://qcm.nexperia.com/Document/DOC-548488/SQR\_202212019F.pdf">https://qcm.nexperia.com/Document/DOC-548488/SQR\_202212019F.pdf</a>

PCNForm.zip: <a href="https://qcm.nexperia.com/Document/DOC-548461/PCNForm.zip">https://qcm.nexperia.com/Document/DOC-548461/PCNForm.zip</a>

DeQuMa.zip: <a href="https://qcm.nexperia.com/Document/DOC-548460/DeQuMa.zip">https://qcm.nexperia.com/Document/DOC-548460/DeQuMa.zip</a>

#### Why do we implement this change?

- To increase efficiency of volume production.
- Capacity expansion in wafer fab
- Continued alignment with world technology trends on state of the art production tools for discrete components

#### **Identification of affected products**

Changed product can be identified by date code after implementation. 8 inch products can be identified by a marker on the die surface.

## **Product availability**

#### **Production**

Planned first shipment: 01 May 2023

Existing inventory will be shipped until depleted

## Sample information

Samples are available upon request

## **Impact**

No impact to the product's functionality anticipated

#### Data sheet revision

No impact to existing datasheet

#### Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 05 Feb 2023. Lack of acknowledgement of the PCN constitutes acceptance of the change.

#### **Additional information**

View Change Notification Online

#### **Contact and support**

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: <a href="mailto:pcn@nexperia.com">pcn@nexperia.com</a>

In case of distribution, please contact you distribution partner.

## **About Nexperia B.V.**

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